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Front Matter: Volume 8607

, "Front Matter: Volume 8607," Proc. SPIE 8607, Laser Applications in
Microelectronic and Optoelectronic Manufacturing (LAMOM) XVIII, 860701 (3
April 2013); doi: 10.1117/12.2025057

SPIE.

Event: SPIE LASE, 2013, San Francisco, California, United States

PROCEEDINGS OF SPIE

Laser Applications in Microelectronic and Optoelectronic Manufacturing (LAMOM) XVIII

**Xianfan Xu
Guido Hennig
Yoshiki Nakata
Stephan W. Roth**
Editors

**4–7 February 2013
San Francisco, California, United States**

Sponsored and Published by
SPIE

Volume 8607

Proceedings of SPIE 0277-786X, V.8607

SPIE is an international society advancing an interdisciplinary approach to the science and application of light.

Laser Applications in Microelectronic and Optoelectronic Manufacturing (LAMOM) XVIII, edited by
Xianfan Xu, Guido Hennig, Yoshiki Nakata, Stephan W. Roth, Proc. of SPIE Vol. 8607, 860701
© 2013 SPIE · CCC code: 0277-786X/13/\$18 · doi: 10.1117/12.2025057

Proc. of SPIE Vol. 8607 860701-1

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Author(s), "Title of Paper," in *Laser Applications in Microelectronic and Optoelectronic Manufacturing (LAMOM) XVIII*, edited by Xianfan Xu, Guido Hennig, Yoshiki Nakata, Stephan W. Roth, Proceedings of SPIE Vol. 8607 (SPIE, Bellingham, WA, 2013) Article CID Number.

ISSN: 0277-786X

ISBN: 9780819493767

Published by

SPIE

P.O. Box 10, Bellingham, Washington 98227-0010 USA

Telephone +1 360 676 3290 (Pacific Time) · Fax +1 360 647 1445

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